



Cookson Electronics

Assembly Materials

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NEWS RELEASE

Release Immediately

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**Cookson Electronics Launches ALPHA® CVP-360
Pb-free Solder Paste with Low-Ag SACX® Alloy**

South Plainfield, NJ -- June 24, 2009 – Cookson Electronics continues its dominant solder paste product development efforts with the launch of ALPHA® CVP-360 Pb-free, no-clean solder paste formulated with its economical low-Ag SACX® 0807 and 0307 alloys. New CVP-360 will deliver high productivity and lowest cost of ownership with excellent in-circuit test yields.

“ALPHA® CVP-360 was developed to offer the highest value to assemblers of consumer electronics products. By enabling the use of lower silver SACX® alloys, CVP-360 can virtually eliminate the price volatility of silver, without eliminating the soldering benefits of silver from the alloy,” said Mitch Holtzer, Cookson’s Global Product manager. “CVP-360 also offers value with extremely high in-circuit pin test yields, and superior spread and wetting versus leading SAC 305 and SAC 405 solder pastes.”

ALPHA® CVP-360 delivers excellent printing characteristics allowing for the use of more economical Type-3 solder powder, even when 12 mil (300 micron) features are being printed using a 5 mil thick (125 micron) stencil. CVP-360 also adds value by allowing high speed printing, and reduced stencil cleaning frequency. This reduces the print cycle time, and lowers the cost of consumables, such as stencil cleaner and under-wipe paper. CVP-360 also has a wide reflow process window, which indicates resistance to head-in-pillow defects. This can also make a difference if older, or lower cost substrates and components are used.

In today's challenging economic conditions, value is more important than ever. ALPHA® CVP-360's high print and reflow process yields, combined with the economy of its low-Ag SACX® alloys with Type-3 powder, allows assemblers to keep SMT manufacturing costs competitive.

More information, go to: (OM-360 product home page on website)

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About Cookson Electronics Assembly Materials

Cookson Electronics Assembly Materials, a Cookson Electronics company, is the global leader in the development, manufacturing and sales of innovative materials used in electronic assembly processes. With a unique worldwide presence in 50 locations throughout the Americas, Europe and the Asia/Pacific region, CEAM supplies a full line of Solder Paste, Stencils, Squeegee Blades, Stencil & PCB Cleaners, Bar Solder, Cored Wire Solder, Wave Soldering

Fluxes, and SMD Adhesives. Cookson Electronics Semiconductor Packaging is the leader in EMC and polymeric materials for semiconductor packaging.

Cookson also offers product technologies for the Photovoltaic market to help lower production costs and increase throughput and yield. Since its founding in 1872, Cookson Electronics has been committed to developing and manufacturing the highest quality soldering materials. That tradition continues today through its innovative products, including its line of environmentally friendly, lead-free electronic assembly products. For more information, visit www.cooksonelectronics.com.

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